



THE TAKE-OFF OF IMMERSION LITHOGRAPHY AT LETI

LETI DAYS LITHOGRAPHY WORKSHOP | Céline Lapeyre | July 6th, 2018

WHY IMMERSION LITHO CELL TODAY @LETI ?

LETI OFFER

Customized R&D program

Dedicated integration blocks

Specific materials qualification

LETI platform access (litho platforms – metrology & defectivity)

Dedicated SW solution deployment

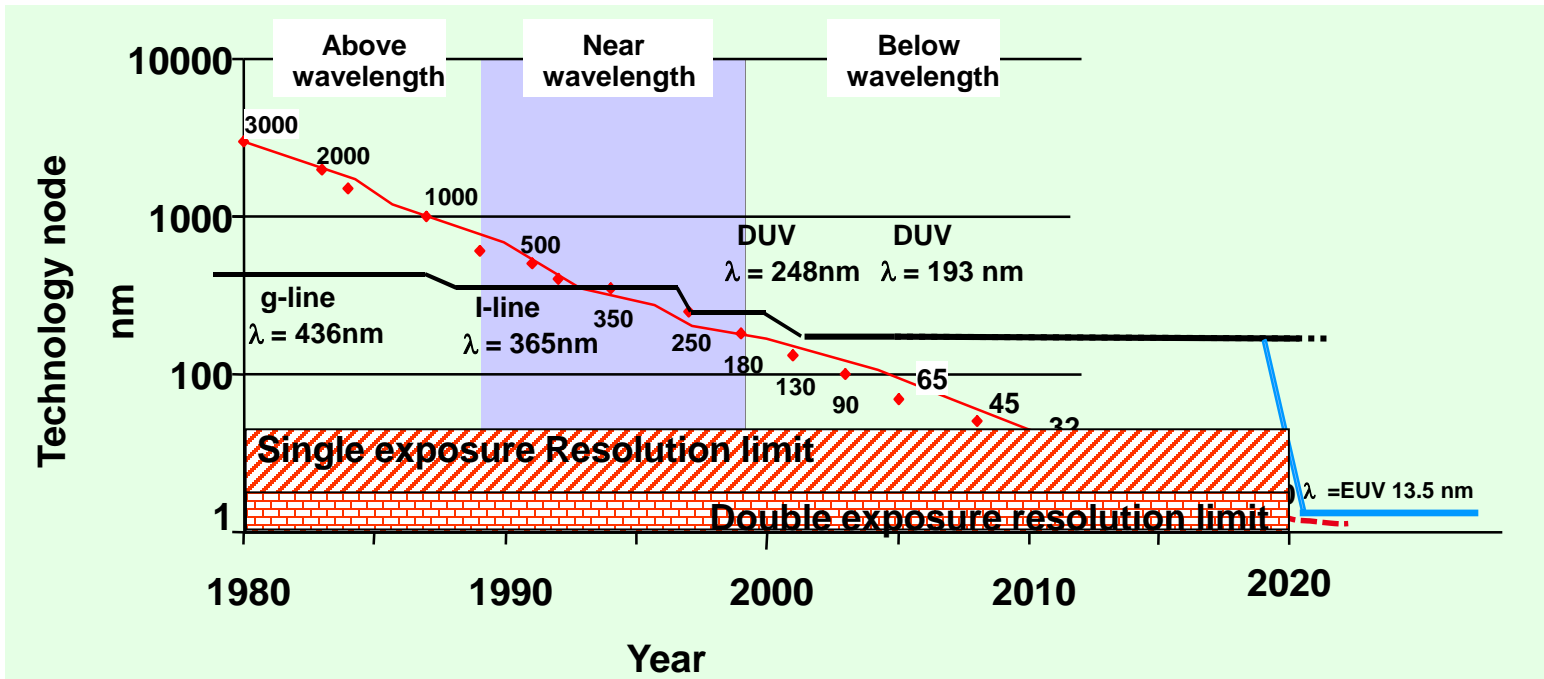
Prototyping & Service

Wafer prototyping with guaranteed cycle time

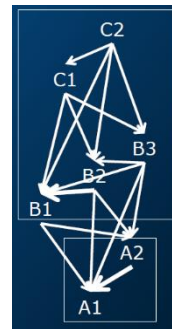
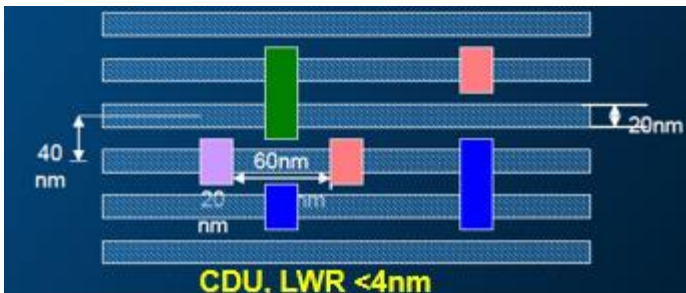
Needs :

- Full patterning autonomy to address **ADVANCED PROGRAM (CMOS 28-14-10-7-5, MEMORY, ...)**
- **Advanced device development at LETI**
- **Support our partners with relevant industrial patterning solution**
- **Full matching with partners lithography tool set (wafers shuttles)**

OPTICAL LITHOGRAPHY



Multipatterning : OVERLAY budget as technological driver



ALIGNMENT → more critical parameter than resolution
→ Metrology needs

IMMERSION LITHOGRAPHY : state of the art, industrial reference

- 1** Immersion Cell Presentation
- 2** Immersion Cell Ecosystem
- 3** Planning
- 4** Starting Projects & Roadmap
- 5** Conclusion

Full patterning autonomy to address advanced LETI programs & support our partners with relevant industrial patterning solution

Track Sokudo DUO DT3000



Scanner NXT:1970Ci

Masks, OPC & Source Optimisation

& METRO-DEF ENVIRONMENT EVOLUTION

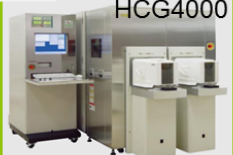
Top view CD-SEM

APPLIED MATERIALS VeritySEM 4i



- Sub-10nm 3D CD-SEM
- high-aspect-ratio imaging, tilted electron beam

HITACHI Inspire the Next HCG4000



- 32nm node dedicated CD-SEM
- + Design Gauge for OPC

Overlay



Archer 600

- Optical overlay metrology for advanced patterning processes at the 1Xnm design nodes (sub-10nm)

Patterned wafer defect inspection & review

- defect capture on 2Xnm/1Xnm memory and logic devices
- scanner defectivity monitoring (PCM)
- Litho PW centering
- Defect capture on 3D & transparent substrate

target 2 tools :
Optical inspection + SEMreview

Consultation under progress

2019

SP2-SP3 surfscan

Scanner baseline



YieldStar S375

- Scanner monitoring (Focus baseline & Overlay baseline)
- on-product overlay and focus using diffraction based overlay (uDBO) and diffraction based focus (DBF) techniques

Scatterometry



NOVA T600

- 3D measurement
- CD measurement

Track Sokudo DUO DT3000



- **Coating** : 18 auto lines + 2SVD system
- **Bakes** : 2 PAHP + 4 PQBH (150°C) +4 PQHH (250°C) +2 PHHH (350°C) + 2 PVQBH (150°C)
- **Positive Tone Development unit (ECO nozzles)**
- **Negative Tone Development unit**
- **Pre-immersion unit** : 1 SOAK (FS) + 2 BSP (backside cleaning)
- **Post-Immersion Rinse unit** : 1 SOAK

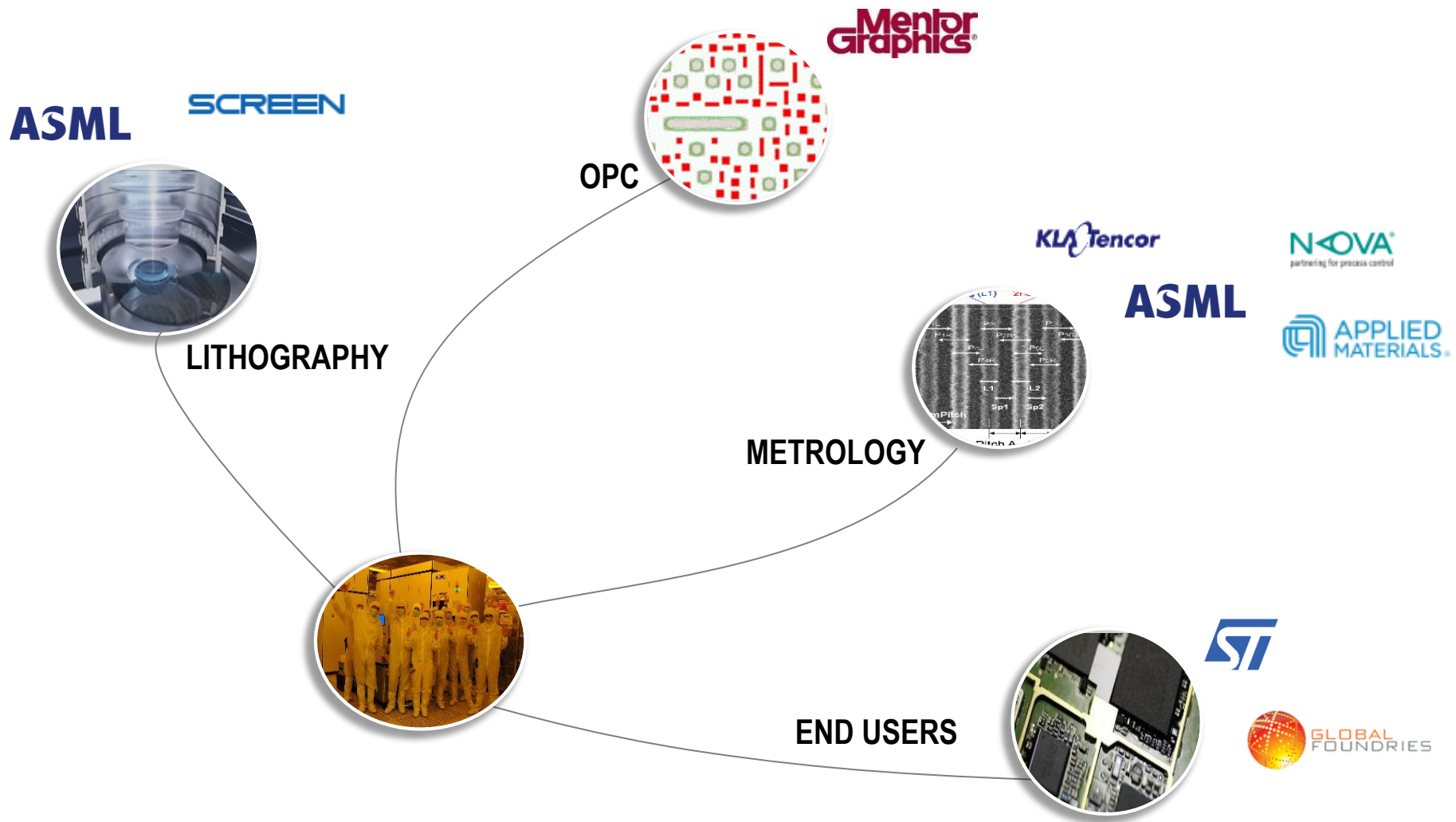


Scanner NXT:1970Ci

- **Imaging performance** : NA 1.35, best resolution in class (CD 38nm ½ pitch)
- **Overlay performance (multi-patterning strategy)**
 - Single Machine Overlay (**SMO**) < 2.0nm
 - Matched Machine Overlay (**MMO**) < 3.5 - 4.5nm
- **Configuration**
 - Flexwave
 - Imaging optimizer
 - Overlay optimizer
 - Litho Computing Platform
 - LithoInsight

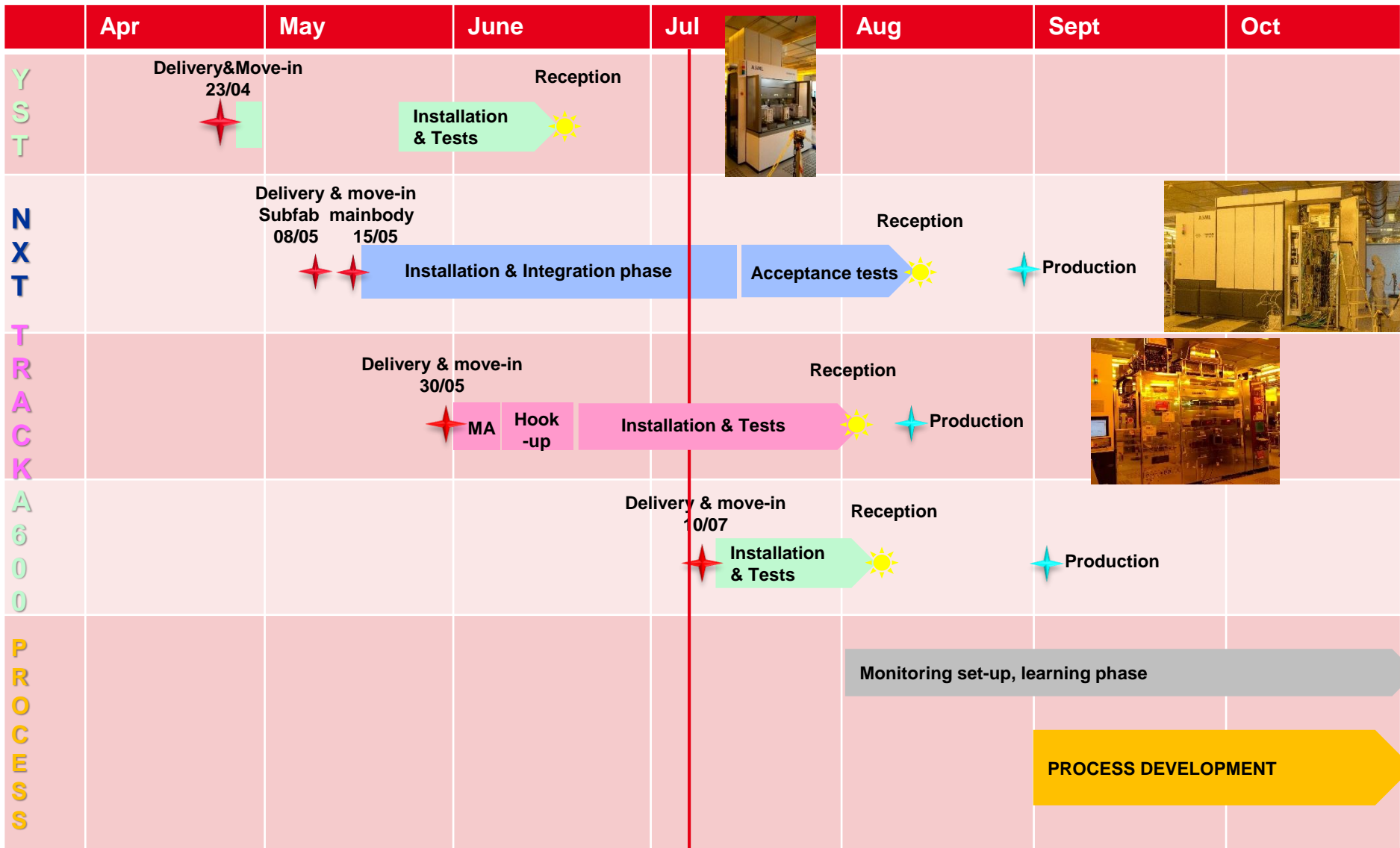


LETI ECOSYSTEM AROUND IMMERSION PROGRAM



IMMERSION TOOLS INSTALLATION PLANNING

2018



STARTING PROJECTS

PCRAM

CMOS ST +
PCM Leti

- WALL

FDSOI

- GATD
- GATE
- CNT
- M1

Photonics on Si

- Si Wave Guide
- Grating
- →2D curved structures

Display

- Polarizer,
Masters for display : Large
dimension
network
patterns
- Work around
stitching

DSA Guide

- Lamellar
approach

Analog devices: resistivity contrast between amorphous and crystalline phase. UNIPOLAR

PCRAM

PHASE CHANGE MATERIAL
HEATER
PCRAM

Binary devices: formation and dissolution of conductive filament. BIPOLAR

CBRAM **OXRAM**

Ag
GeS₂
W plug
← Filament
50nm

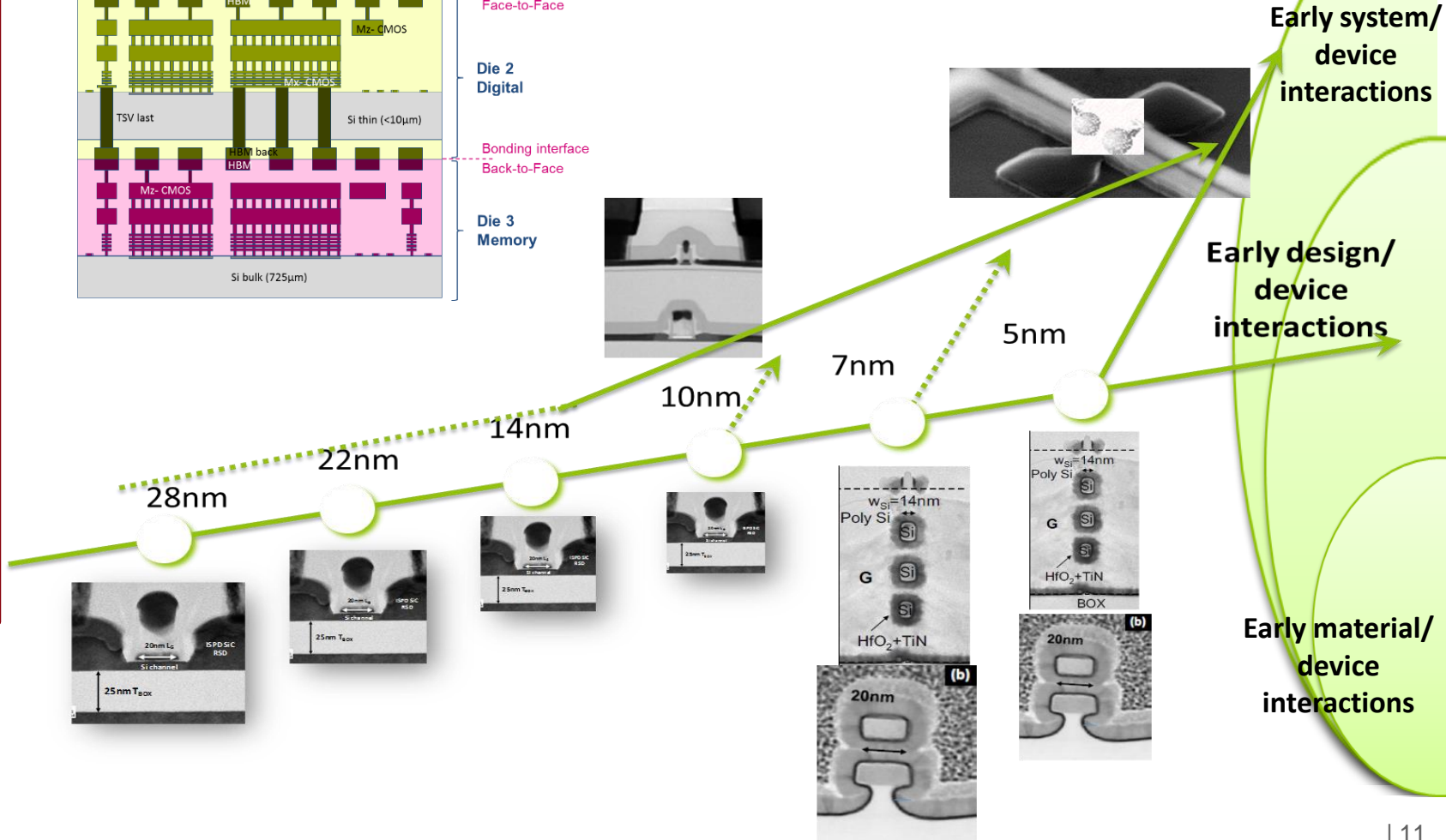
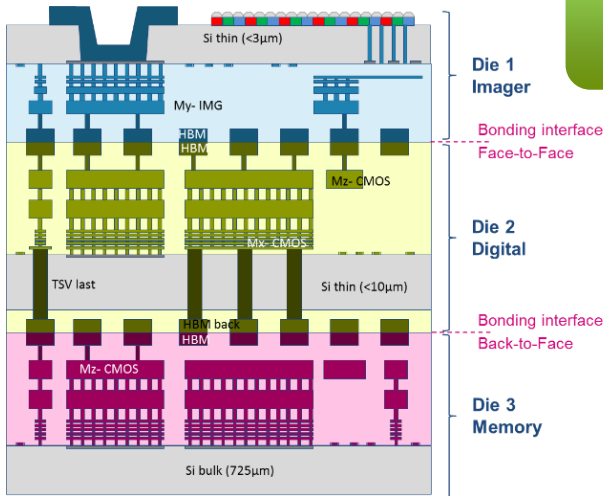
200 nm
H₂O₂
NULL

M.Suri, et. al, IEDM 2011
O.Bichler et al. IEEE TED 2012
D.Garbin et al., IEEE Nano 2013
S. La Barbera et al., Advanced Electronic Materials 2018

M.Suri et al., IEDM 2012
D.Garbin et al. IEDM 2014
D. Garbin et al., IEEE TED 2015
T. Werner et al., IEDM 2016
E. Vianello et al.; IMW 2017

Support these developments with aggressive resolution

INTEGRATE & STACK FUNCTIONALITIES 28nm – 12nm technology nodes baselines

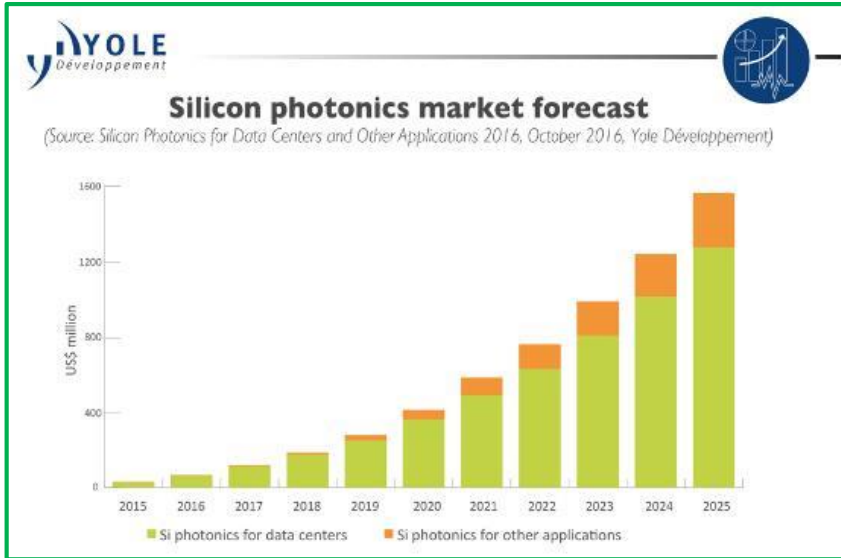


FDSOI

A CHALLENGING PERSPECTIVE AROUND PHOTONIC ?

Photonic

- Si Wave Guide
- Grating → 2D curved structures

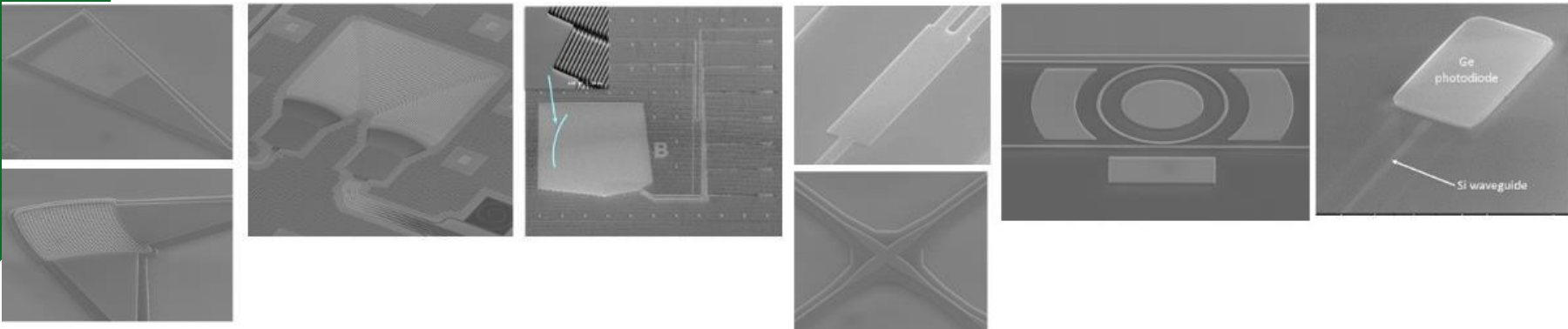
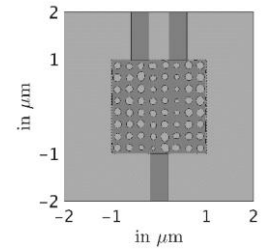


RESOLUTION

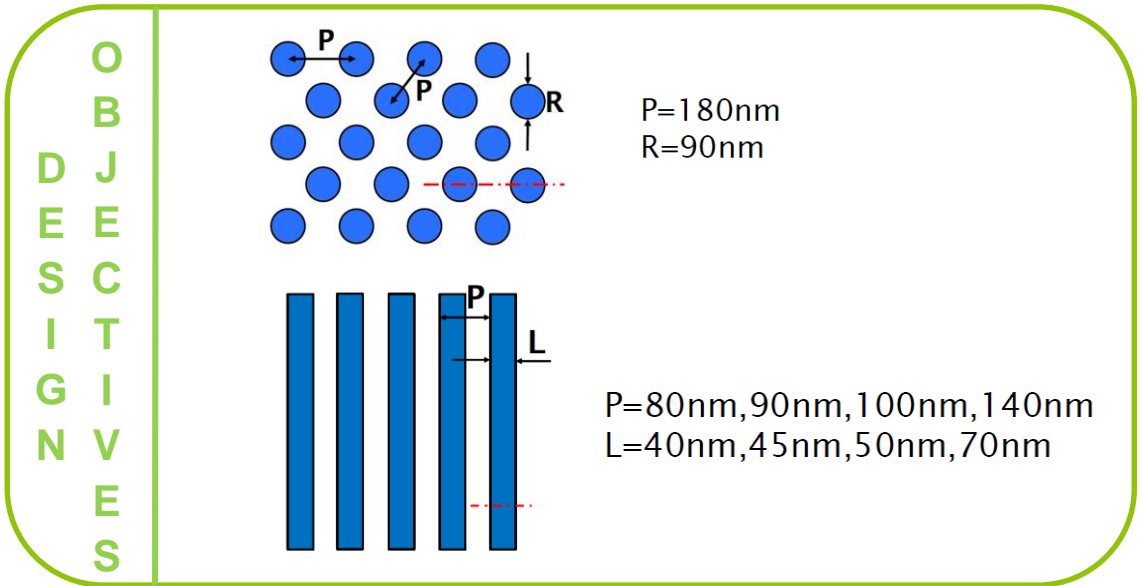
ROUGHNESS

2D CURVES RET

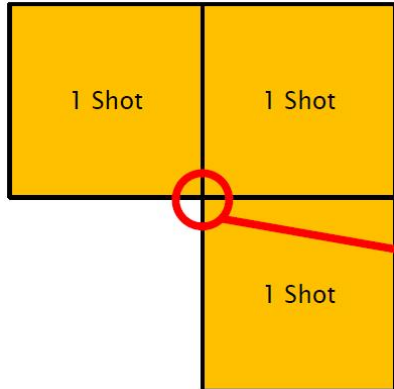
SPECIFICATION & TOLERANCES



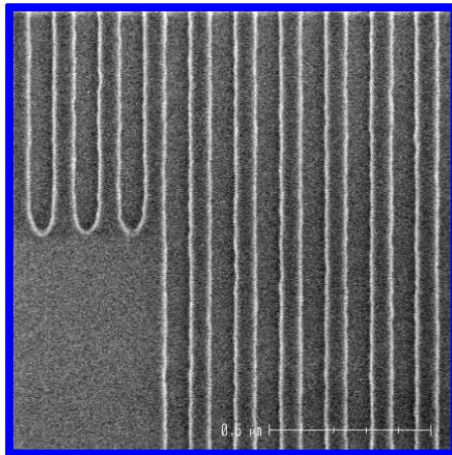
DISPLAY



- Display
- Large surface master
 - Grating
 - Stitching



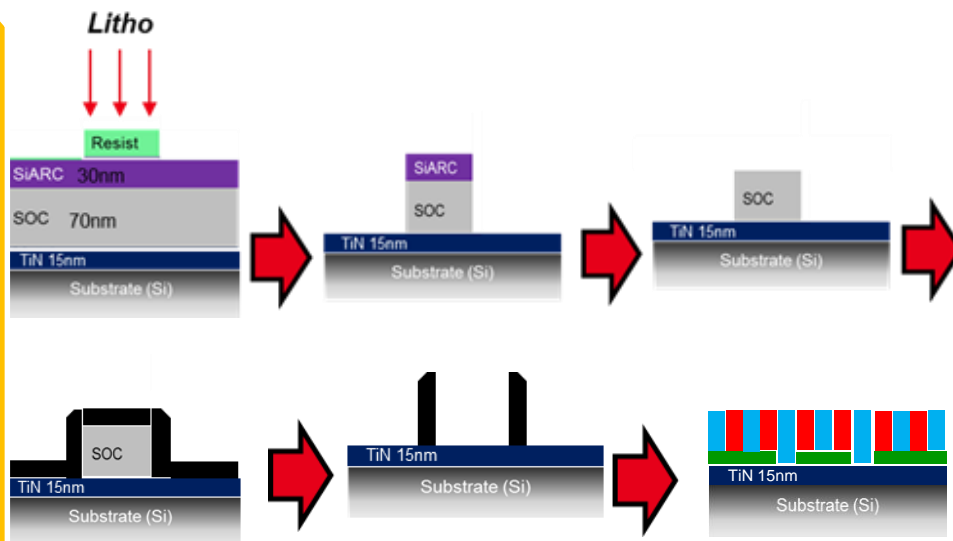
Mapping : full 300mm coverage



Stitching : not visible

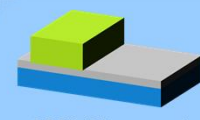
DSA Guide

Lamellar approach

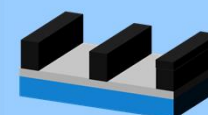
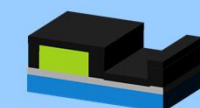


L18	x2	x3	x4
CD_{line} (nm)	27	45	63
Pitch (nm)	72	108	144

Spacer flow



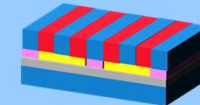
193i lithography



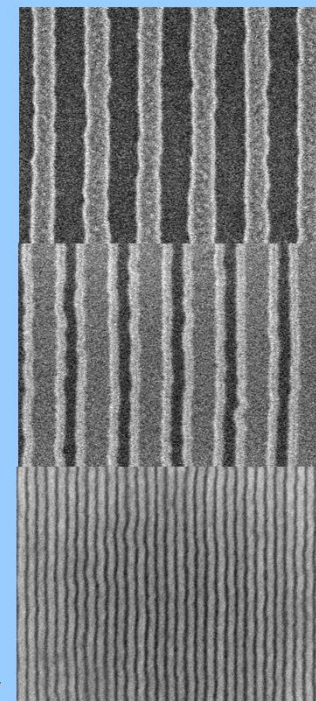
Spacer patterning



DSA

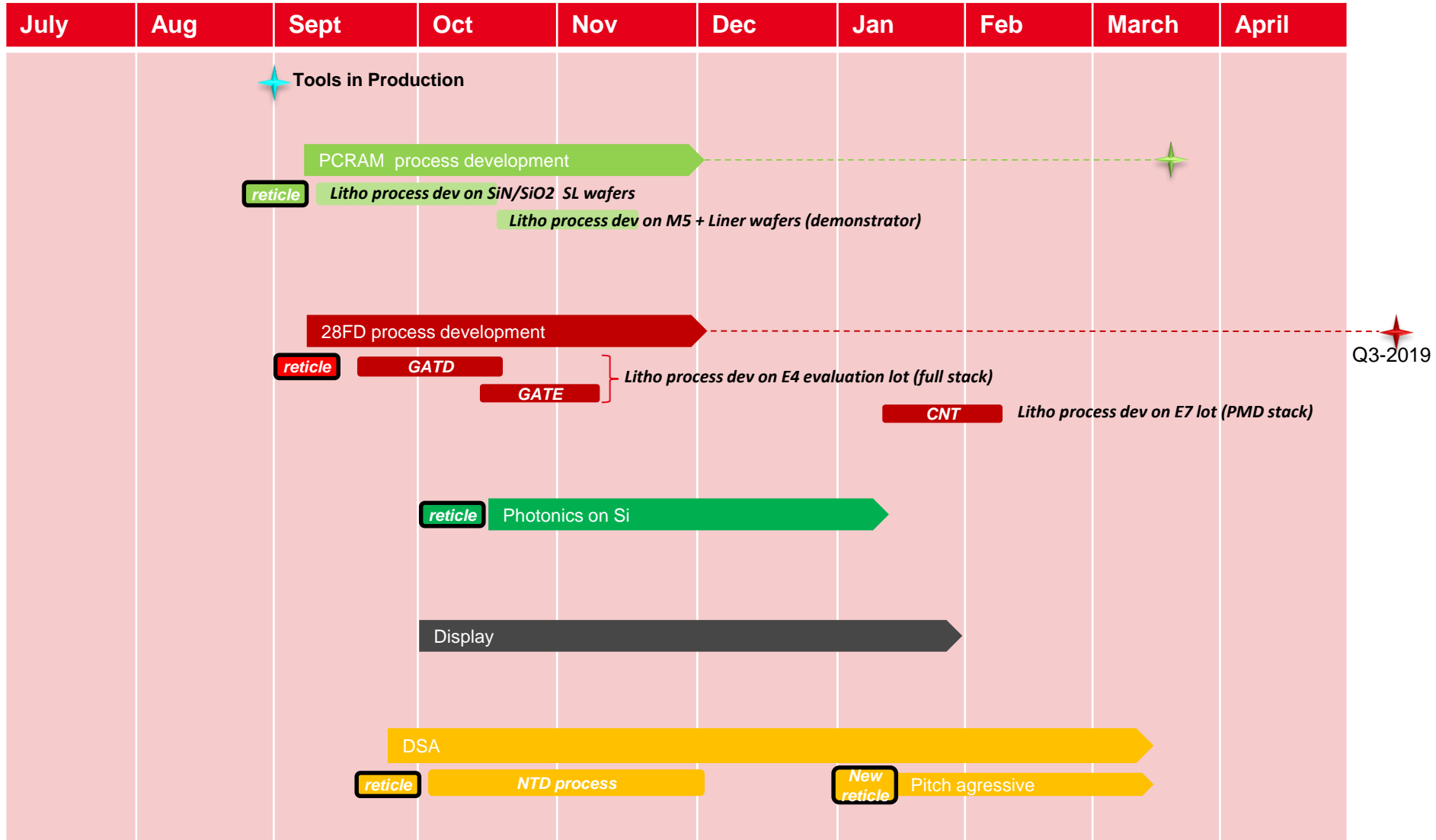


BCP self-assembly



Goal: Implement a vehicule test for chemoepitaxy of High- χ BCP ($L_0 < 20$ nm)

IMMERSION CELL : 1ST PROGRAM STARTUP

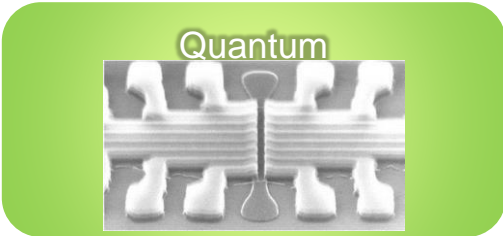
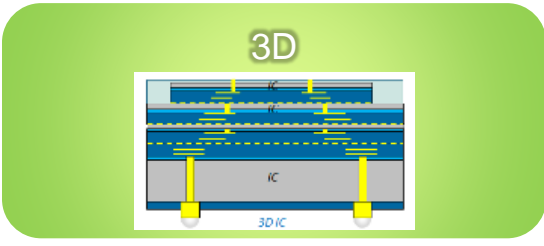
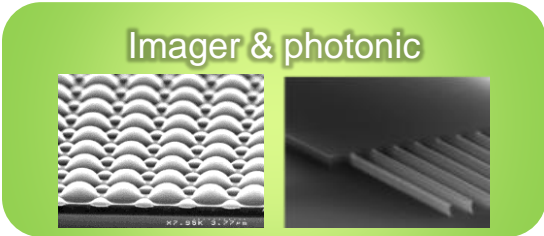
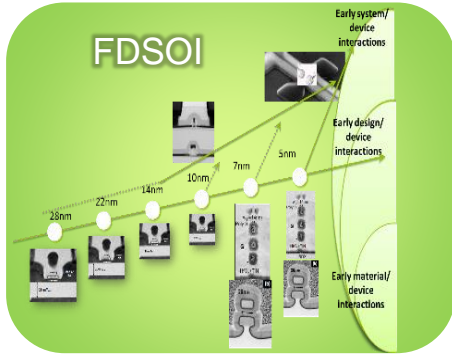
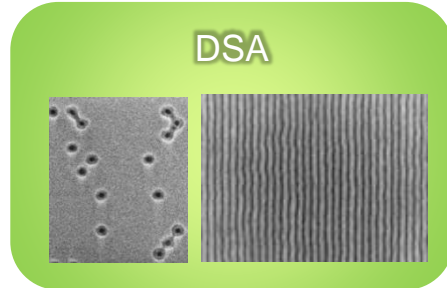
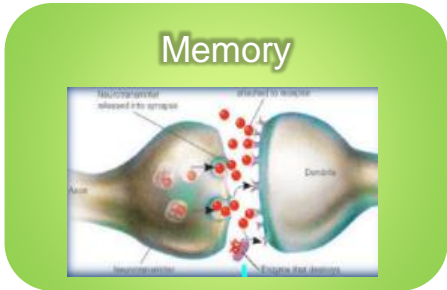


Q3-2019

CONCLUSION

- Immersion cell investment @LETI is a big challenge
- Strong start-up in September with challenging projects

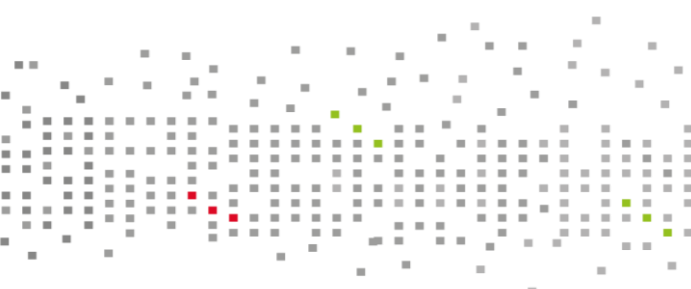
Our objective :
Support the next wave of innovations with best-in-class lithography option



ACKNOWLEDGMENTS

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Leti, technology research institute

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